

## Materials Declaration

<b>Package</b>	LFCSP
<b>Body Size</b>	6 X 6 X 0.85 (3.70 mm exposed pad)
<b>LeadCount</b>	36
<b>Option</b>	Pb-free

### Molding Compound

Item	% of Compound	Weight (g)	PPM
SiO2 Filler	84.0	3.63 E-02	392045
Multiaromatic Resin	16.0	6.91 E-03	74678
Subtotal		4.32 E-02	466723

### Molding Compound

Item	PPM	Method
Pb	Not Detected	EPA Method 3051A13052. ICP-OES.
Cd	Not Detected	EPA Method 3051A13052. ICP-OES.
Hg	Not Detected	EPA Method 3051A13052. ICP-OES.
Cr+6	Not Detected	EPA Method 3060A & 7196A. UV-VIS.
PBB	Not Detected	EPA Method 3540C/ 3550C. GC/MS.
PBDE	Not Detected	EPA Method 3540C/ 3550C. GC/MS.

### Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	97.50	4.19 E-02	452572
Fe	2.35	1.03 E-03	11148
Zn	0.12	5.20 E-05	562
P	0.03	1.30 E-05	140
Subtotal		4.30 E-02	464422

### Die Attach Material

Item	PPM	Method
Pb	Not Detected	EPA Method 3051A13052. ICP-OES.
Cd	Not Detected	EPA Method 3051A13052. ICP-OES.
Hg	Not Detected	EPA Method 3051A13052. ICP-OES.
Cr+6	Not Detected	EPA Method 3060A & 7196A. UV-VIS.
PBB	Not Detected	EPA Method 3540C/ 3550C. GC/MS.
PBDE	Not Detected	EPA Method 3540C/ 3550C. GC/MS.

### Internal Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Ag	100.0	4.32 E-04	4667

### External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	100.0	1.02 E-03	11051

### Bond Wires

Item	% of Wire	Weight (g)	PPM
Au	99.99	1.86 E-03	20071

### Chip

Item	% of Chip	Weight (g)	PPM
Si	100.0	2.39 E-03	25861

### Die Attach Material

Item	% of Die Attach	Weight (g)	PPM
Ag	70.0	4.67 E-04	5045
Resin	21.0	1.40 E-04	1512
Metal Oxide	3.0	2.00 E-05	216
Amine	3.0	2.00 E-05	216
Gamma Butyrolactone	3.0	2.00 E-05	216
Subtotal		6.67 E-04	7205

### Package Totals

Weight (g)	PPM
9.26 E-02	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



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